



HH-D01 NearLink Development Board Product manual

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1 Overview



Figure 1-1 HH-D01 NearLink development board

HopeRun HH-D01 development board is a highly integrated 2.4GHz SoC Wi-Fi, BLE and SLE Combo chip development board that integrates IEEE802.11b/g/n/ax baseband and RF circuits. The RF circuit includes the power amplifier PA, low noise amplifier LNA, RF balun, antenna switch and power management modules, the motherboard adopts stamp hole interface, PCB onboard antenna, small size, rich external interfaces, easy to develop and integrate. It is suitable for IoT fields such as smart homes, smart wearables, medical monitoring, industrial testing, electric power and water conservancy, and smart agriculture.

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2 Product Highlights

- Flexible networking capabilities
- ♦ Supports three networking methods: Wi-Fi/BLE/SLE
- Complete network support
- ♦ Support IP4/IPv6 network functions
- ♦ Support CoAP/MQTT/HTTP/JSON basic components
- Powerful security engine
- Supports multiple hardware encryption algorithms, secure storage, secure boot, and memory isolation features
- Open operating system
- Open operating system Oniro provides an open, efficient and secure system development and operating environment

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3 Technical parameters

Table 3-1 HH-D01 NearLink development board technical parameters

Classificatio	describe			
n				
"				
	Solution based on HiSilicon NearLink WS63, highly integrated 2.4GHz SoC			
SoC	Wi-Fi, BLE and SLE Combo chip			
	Integrated high-performance 32bit microprocessor, hardware security			
	engine and rich peripheral interfaces, including SP1, OSPI, UART, I2C,			
	PWM, GPIO and multi-channel ADC; the chip has built-in SRAM and Flash,			
	can run independently, and supports Run programs on Flash			
Operating				
system	Supports Oniro and more			
Communicat				
	Supports reliable communication algorithms such as TPC, automatic rate,			
ion ability	and weak interference immunity in complex environments			
Networking				
capabilities	Supports three networking methods: Wi-Fi, BLE or SLE			
	Support IPv4/IPv6 network functions			
Network	Support DHCPv4/DHCPv6 Client/Server			
 Support DNS Client function 				
capabilities	Support mDNS function			
	Support CoAP/MQTT/HTTP/JSON basic components			
	Hardware implementation of AES128/256 encryption and decryption			
	algorithm			
	Hardware implementation of HASH-SHA256 and HMAC_SHA256			
	algorithms			
	Hardware implementation of RSA and ECC signature verification			
Security	algorithms			
capabilities	Hardware implements true random number generation, meeting FIPS140-			
	2 random testing standards			
	Hardware supports TLS/DTLS acceleration			
	Hardware supports national secret algorithms SM2, SM3, SM4			
 Internally integrated EFUSE, supporting secure storage, secure boot, 				
hardware ID				



• Internally integrated MPU features support memory isolation features

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4 packing list

Table 4-1 Packing list

serial	content	quantity
number		
1	HH-D01 NearLink Development Board	1
2	Type-C USB data cable	1

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